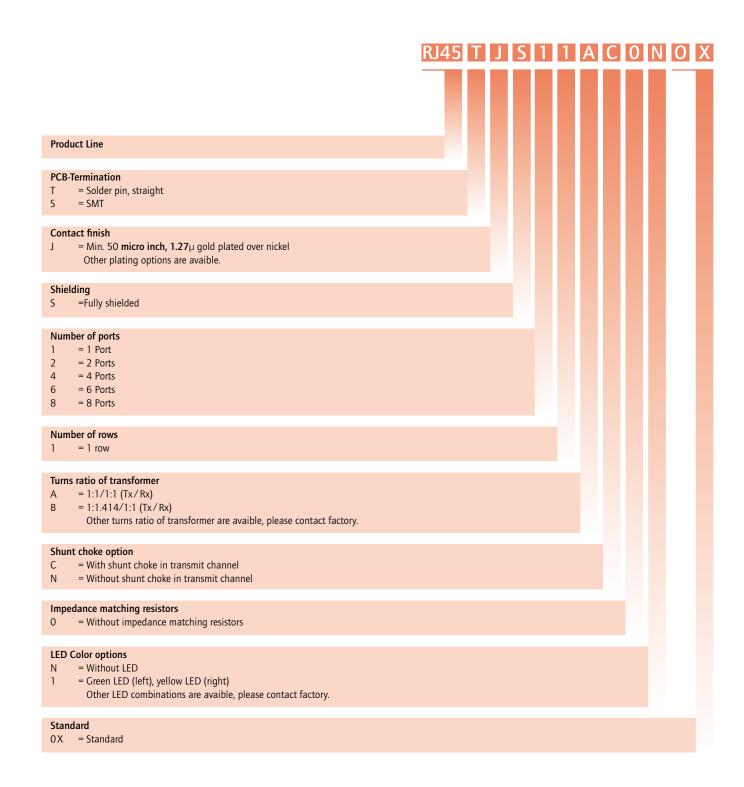
PART NUMBER CREATOR

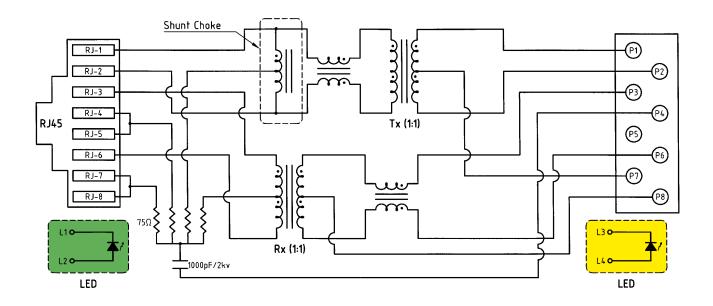


TECHNICAL DATA

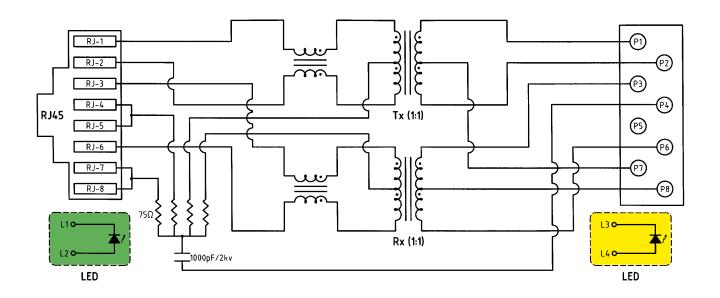
Specifications					
Housing, solder pin, straight	Polyester glass filled, black, UL94 V-O				
Housing, SMT-Termination	Nylon 46 glass filled, black, UL94 V-O				
Shielding	.008"/0.20 mm thick copper alloy				
Contact material	.014"/0.35 mm thick copper alloy				
Mating area plating	50μ"/1.27 μm gold min. over 30μ"/0.76 μm min. nickel				
Solder tails plating	Tin plated				
OCL (Open Circuit Inductance)	Min. 350 μH at 8mA DC bias				
Leakage inductance	Max. 0.35 μH				
Inter-winding capacitance	Max. 25 pF				
DC-Resistance	Max. 1.0 Ω				
Turns ratio	$1:1/1:1 \pm 3\%$ or Tx/Rx = $1:1.414/1:1 \pm 3\%$				
Rise time and fall time	3.0 ns (typical)				
Mating force	Max. 22 N				
Retention force	Min. 89 N				
Mating cycles	Min. 1 000				
Contact resistance	Max. 20 mΩ				
Insulation resistance	Min. 1000 mΩ				
Dielectric with standing voltage	1 500V ms (Signal to Shield)				
Current rating	Max. 0,05A				
Spezification at 25°C (Operating temperature -40°C to +85°C)					
Insertion loss	0.1-100 MHZ	1.0 dB max			
Return loss	0.1-30 MHZ	20.0 dB Type			
	60 MHZ	15.0 dB Type			
	80 MHZ	12.0 dB Type			
Next near and cross talk	0.1-30 MHZ	50.0 dB Type			
	60 MHZ	45.0 dB Type			
	100 MHZ	40.0 dB Type			
Differential to common mode rejection	60 MHZ	40.0 dB Type			
	100 MHZ	35.0 dB Type			
	00.1111	25.0 10.7			
Common mode rejection ration	60 MHZ	35.0 dB Type			
	100 MHZ	30.0 dB Type			
Hi-Pot	1500 Vrms	60 sec.			
Standard-LED					
Color	Green	Yellow			
Wassa Israedh	r.c.r	FOF			
Wave length	565 nm	585 nm			
Forward voltage with I _F =20 mA	2.6 V (max)	2.6 V (max)			
I of ward voltage with IF-20 IIIA	2.6 V (max) 2.1 V (Type)	2.0 V (Type)			
	Z.I v (Type)	2.0 v (1ype)			
Reserve voltage with I _R =10 μA	5.0 V (Type)	5.0 V (Type)			
meserve voltage with ig-10 μA	J.O V (Type)	3.0 v (1ype)			
Luminous intensity with I _F =20 mA	15 mcd (min)	20 mcd (min)			
Laminous intensity with it 20 m/s	25 mcd (Type)	30 mcd (Type)			
	23 med (Type)	Jo med (1996)			

SCHEMATICS

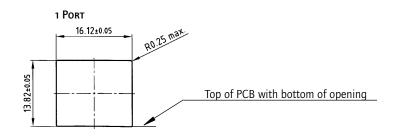
Schematic of magnetic Circuit with Tx/Rx = 1:1/1:1 or Tx/Rx = 1:1.414/1:1 - Turns Ratio, additional shount Chok, $4x0,75\Omega$ Terminal Resistors - 1000pF/2kv Capacitor and LEDs (Optional)

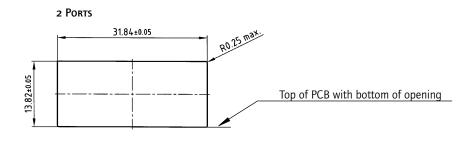


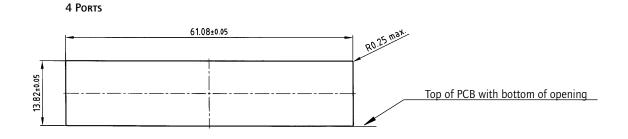
Schematic of magnetic Circuit with Tx/Rx = 1:1/1:1 or Tx/Rx = 1:1.414/1:1 - Turns Ratio, additional $4x0,75\Omega$ Terminal Resistors - 1000pF/2kv Capacitor and LEDs (Optional).

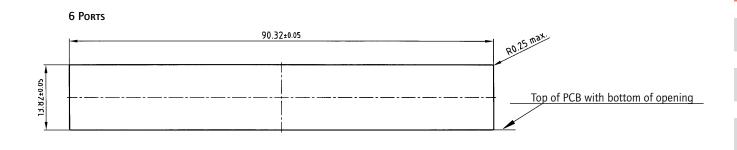


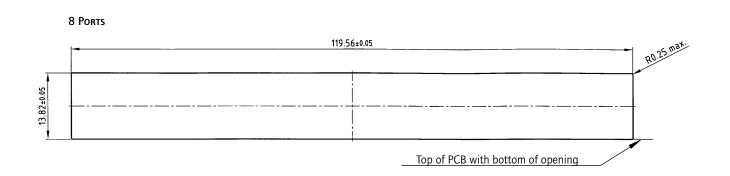
RECOMMENDED PANEL CUT-OUT





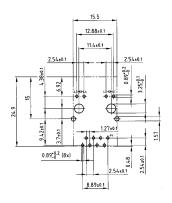




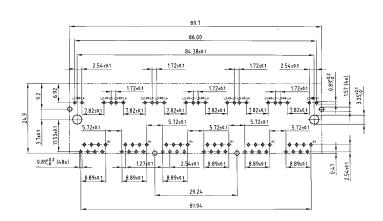


PCB LAYOUT FOR SOLDER PIN STRAIGHT

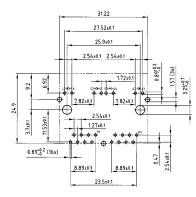
1 Port



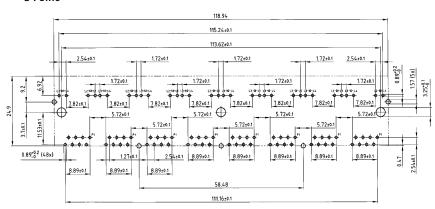
6 Ports



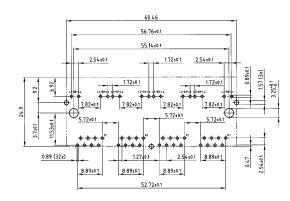
2 Ports



8 Ports



4 Ports

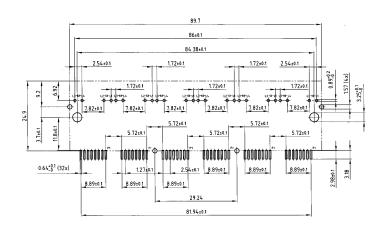


PCB LAYOUT FOR SMT-TERMINATION

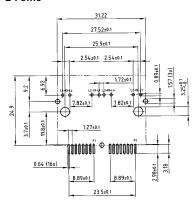
1 Port

15.5 12.88±0.1 0.64^{+0.1}₋₀ (8x) 3.18 1.27±0.1 8.89±0.1

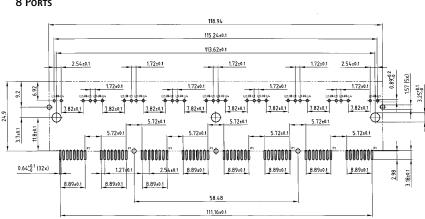
6 Ports



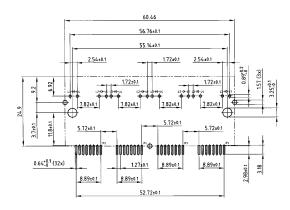
2 Ports



8 Ports



4 Ports



SOLDER PROFILE

Connector Type	Preheating		Solder terminal dipping parameters	
	max. Temperature	Duration	max. Solder bath Temperature	max. Terminal Immersion Time
Filter D-SUB	100°C	30s	260°C	5s
Combo D-SUB Filter	120°C	120s	260°C	5s
Filter D-SUB Water Resistant	100°C	30s	240°C	5s
Combo D-SUB Water Resistant	120°C	120s	240°C	5s
D-SUB Water Resistant	120°C	120s	240°C	5s
D-SUB Solid Body Type Water Resistant	150°C	180s	265°C	8s
RJ45 Modular Jack Filtered	150°C	180s	265°C	8s
Filter Plates	150°C	180s	265°C	8s

Recommended wave-solder parameters for CONEC connectors.